

10-Bit 70MSPS Sampling Analog-to-Digital Converter

nAD1070-18

FEATURES

- 1.8V power supply
- SNR typ 59dB for $(f_{in} = 10\text{MHz})$
- Low power (45mW @ 1.8V and 70MSPS)
- Frequency dependent biasing
- Internal Sample/Hold
- Differential input
- Low input capacitance
- Power Down and Sleep Mode

APPLICATIONS

- Imaging
- Test equipment
- Computer scanners
- Wireless communication
- Powerline communication
- Set top boxes
- Video products

GENERAL DESCRIPTION

The nAD1070-18 is a compact, high-speed, low power 10-bit monolithic analog-to-digital converter, implemented in a 0.18 μ m single poly CMOS process with MiM capacitor option. The converter includes a high bandwidth sample and hold. Using internal references, the full scale range is ± 0.75 V. The full scale range can be set between ± 0.5 V and ± 0.75 V using external references. It operates from a single 1.8V supply. Its low distortion and high dynamic range offers the performance needed for demanding imaging, multimedia, telecommunications and instrumentation applications. The bias current level for the ADC is automatically adjusted based on the clock input frequency. Hence, the power dissipation of the device is continuously minimised for the current operation frequency.

QUICK REFERENCE DATA

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
$V_{ m DD}$	Supply voltage		1.6	1.8	2.0	V
I_{DD}	Supply current (70 MSPS)			25		mA
P_D	Power dissipation (10 MSPS)	Except digital output drivers		8		mW
P_D	Power dissipation (70 MSPS)	Except digital output drivers		45		mW
DNL	Differential nonlinearity	f _{IN} =0.9991MHz			±0.5	LSB
INL	Integral nonlinearity	f _{IN} =0.9991MHz			±0.75	LSB
f_S	Conversion rate			70		MHz
N	Resolution				10	bit

Table 1. Quick reference data



GENERAL DESCRIPTION (Continued)

The nAD1070-18 has a pipelined architecture - resulting in low input capacitance. Digital error correction of the 9 most significant bits ensures good linearity for input frequencies approaching Nyquist. The nAD1070-18 is compact. The core occupies less than 0.9mm^2 of die area in a standard single poly $0.18 \mu \text{m}$ CMOS process. The fully differential architecture makes it insensitive to substrate noise. Thus it is ideal as a mixed signal ASIC macro cell.

BLOCK DIAGRAM EXTREF BIAS0 BIAS1 _INN INP VCM CK0 CKBUS<3:0> CK0B **CLOCK** CK2 IN_CORR<17:0> CK2B CKCORR<1:0> CORR_LOG BIT<9:0>

Figure 1. Block diagram nAD1070-18



ELECTRICAL SPECIFICATIONS

(At $T_A = 25$ °C, $V_{DD} = 1.8V$, Sampling Rate = 70MHz, Input frequency = 10MHz, Differential input signal, 50% duty cycle clock unless otherwise noted)

Symbol	Parameter (condition)	Test Level	Min.	Тур.	Max.	Units
	DC Accuracy		l l		l	L
DNL	Differential Nonlinearity					
	$f_{IN} = 0.9991 \text{ MHz}$	IV		±0.5		LSB
INL	Integral Nonlinearity					
	$f_{IN} = 0.9991 \text{ MHz}$	IV		±0.75		LSB
V _{OS}	Midscale offset			± 1		%FS
CMRR	Common Mode Rejection Ratio			-59		dB
$\epsilon_{ m G}$	Gain Error			±1		%FS
-0	Dynamic Performance	1	l l		l	
SNR	Signal to Noise Ratio (without harmonics)					
	$f_{IN} = 10 \text{ MHz}$	IV	56	59		dBFS
	$f_{IN} = 40 \text{ MHz}$	IV	55	58.5		dBFS
SINAD	Signal to Noise and Distortion Ratio					
	$f_{IN} = 10 \text{ MHz}$	IV		59		dBFS
SFDR	Spurious Free Dynamic Range					
	$f_{IN} = 10 \text{ MHz}$	IV		69		dB
	$f_{IN} = 40 \text{ MHz}$	IV		57		dB
	Analog Input	1			1	1
V_{FSR}	Input Voltage Range (differential)	IV		±0.75		V
V_{CMI}	Common mode input voltage	IV		0.9		V
C_{INA}	Input Capacitance (from each input to			1.5		pF
	ground)					
	Reference Voltages	1	T T		1	
V _{REFNI}	Internal reference voltage on pin 10	IV		0.525		V
V_{REFPI}	Internal reference voltage on pin 11	IV		1.275	100	V
	Internal reference voltage drift				100	ppm/°C
V _{REFNO}	Negative Input Voltage	IV		0.525		V
V _{REFPO}	Positive Input Voltage	IV		1.275		V
V _{REFP} -V _{REFN}		IV		0.75		V
V_{CM}	Common mode output voltage	IV		0.9		V
	Switching Performance	***	1 1	70	1	1.000
F_S	Conversion Rate	IV		70		MSPS
	Pipeline Delay	IV		6		Clocks
t _{AP}	Aperture delay, IP	V		0.9		ns
t _h	Output hold time, IP	V	+	0.5		ns
t _d	Output delay time, IP Aperture delay, with bonding pad	V	1	1.0		ns
t _{AP}	Output hold time, with bonding pad	V	1	1.0		ns
t _h	Output delay time, with bonding pad	V	1	4.0		ns ns
rd.		, v	1	7.0	1	115
V	Digital Inputs Logic "0" voltage	IV	1		0.4	17
V _{IL}	Logic 0 voltage Logic "1" voltage	IV	AV 0.4		0.4	V
V _{IH}	Logic '1 Voltage Logic "0" current (V _I =V _{SS})	IV	AV_{DD} -0.4		±10	
I _{IL}	Logic "1" current $(V_I = V_{SS})$ Logic "1" current $(V_I = V_{DD})$	IV	1			μΑ
I _{IH}	. 1 25				±10	μA
C_{IND}	Input Capacitance	IV		5	l	pF

(table continued on next page)

PRODUCT SPECIFICATION



nAD1070-18 10 Bit 70 MSPS Sampling ADC IP

	Digital Outputs					
V_{OL}	Logic "0" voltage (I = 2 mA)	IV		0.2	0.4	V
V_{OH}	Logic "1" voltage (I = 2 mA)	IV	85% OV _{DD}	90% OV _{DD}		V
	Power Supply					
$V_{ m DD}$	Supply voltage	V	1.6	1.8	2.0	V
I_{DD}	Supply current (except digital output)	IV				mA
V_{SS}	Supply voltage			GND		
P_{D}	Power dissipation (except digital output) (10 MSPS)	IV		8		mW
P_{D}	Power dissipation (except digital output) (70 MSPS)	IV		45		mW
P _D	Power dissipation (except digital output) Power Down Mode 2)	IV		45		μW
P _D	Power dissipation (except digital output) Sleep Mode	IV		655		μW
AV_{DD} - DV_{DD1}	Analog power – digital power pins		-0.2		+0.2	V
OV_{DD}	Output driver supply voltage		1.6	1.8	2.0	V
T	Ambient operating temperature		-40		+85	°C

Table 2. Electrical specifications

Test Levels

Test Level I: 100% production tested at +25°C

Test Level II: 100% production tested at +25°C and sample tested at specified temperatures

Test Level III: Sample tested only

Test Level IV: Parameter is guaranteed by design and characterization testing

Test Level V: Parameter is typical value only

Test Level VI: 100% production tested at +25°C. Guaranteed by design and

characterization testing for industrial temperature range

ABSOLUTE MAXIMUM RATINGS

$\label{eq:supply voltages} \begin{split} AV_{DD} & \dots - 0.2V \text{ to } +2.2V \\ DV_{DD1} & \dots - 0.2V \text{ to } V_{DD} + 0.2V \\ OV_{DD} & \dots - 0.2V \text{ to } V_{DD} + 0.2V \end{split}$	Temperatures Operating Temperature40 to +85°C Storage Temperature 65 to +125°C
Input voltages	
Analog In $0.2V$ to $AV_{DD} + 0.2V$	
Digital In $-0.2V$ to $V_{DD} + 0.2V$	
REF_{P} 0.2V to $AV_{DD} + 0.2V$	
REF _N $0.2V$ to $AV_{DD} + 0.2V$	
CLOCK 0.2V to $V_{DD} + 0.2V$	

Note: Stress above one or more of the limiting values may cause permanent damage to the device.

¹⁾ See Figure 5.

²⁾ Power Down Mode is only available for IP version of nAD1070-18.



PIN FUNCTIONS

Pin Name	Description			
INP INN	Differential input signal pins. Common mode voltage: 0.9V			
REFP REFN	Reference input pins. Bypass with 100nF capacitors close to the pins. See Application Information below.			
BIAS0, BIAS1	Digital inputs for max. sampling rate programming.			
	BIAS1=0, BIAS0=0: Sleep mode (power save)			
	BIAS1=0, BIAS0=1: - 12.5% bias			
	BIAS1=1, BIAS0=0: +12.5% bias			
	BIAS1=1, BIAS0=1: Typ. Bias			
	The bias setting is automatically performed based on the clock input frequency. This function should be used ONLY if another bias setting than typical must be used.			
CLOCK	Clock input			
VCM	Common mode voltage output			
BIT9 - BIT0	Digital outputs (MSB to LSB)			
OR	OverRange. High if all outputs are zeros or ones. Available on IP.			
OUTEN	Enable digital outputs (Keep low for active outputs)			
EXTREF	Disable internal references (Keep low for internal references)			
PD	Power Down (Keep low for normal operation) Available on IP or with bonding option.			
V_{DD}	Power pins for on chip power			
V _{SS}	Ground pins			
OV_{DD}	Power pins for output drivers			

Table 3. Pin functions

PIN ASSIGNMENT

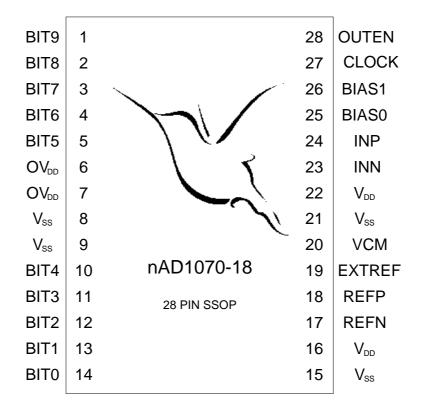


Figure 2. Pin assignment for the 28 pin package used for samples



IP BLOCK LAYOUT

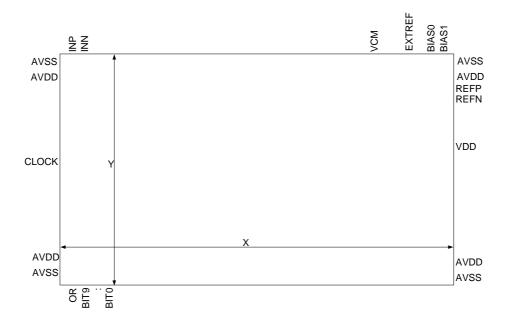


Figure 3. Size and pin placement for nAD1070-18. The height and width of the layout is X =1208 μ m and Y=711 μ m respectively in the 0.18 μ m CMOS process.

TIMING DIAGRAM

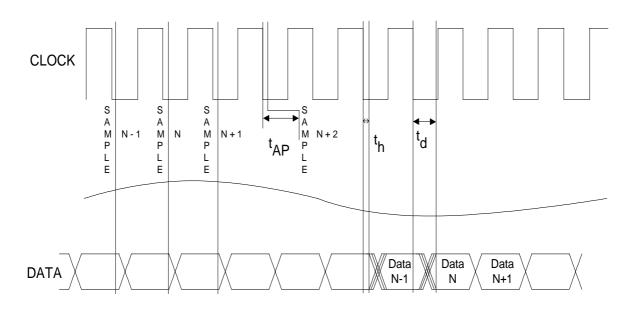


Figure 4. Timing diagram



INPUT SIGNAL RANGE

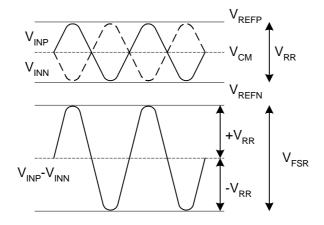


Figure 5. Definition of full scale range

DEFINITIONS

Data sheet status					
Objective product specification This datasheet contains target specifications for product development.					
Preliminary product specification	This datasheet contains preliminary data; supplementary data may be published from Nordic VLSI ASA later.				
Product specification	This datasheet contains final product specifications.				
Limiting values					
Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Specifications sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.					
Application information					
Where application information is given, it is advisory and does not form part of the specification.					

Table 4. Definitions

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Nordic VLSI ASA customers using or selling these products for use in such applications do so at their own risk and agree fully indemnify Nordic VLSI ASA for any damages resulting from such improper use or sale.



APPLICATION INFORMATION

References

The nAD1070-18 has a differential analog input. The input range is determined by the voltages V_{REFP} and V_{REFN} applied to reference pins REFP and REFN respectively, and is equal to $\pm (V_{REFP}-V_{REFN})$. Externally generated reference voltages connected to REFP and REFN should be symmetrical around 0.9V. The input range can be defined between ± 0.5 V and ± 0.75 V. The references should be bypassed as close to the converter pins as possible using 100nF capacitors in parallel with smaller capacitors (e.g. 1nF) (to ground).

Analog input

The input of the nAD1070-18 can be configured in various ways - dependent upon whether a single ended or differential, AC- or DC-coupled input is wanted.

AC-coupled input is most conveniently implemented using a transformer with a center tapped secondary winding. The center tap is connected to the CM-node, as shown in figure 6. In order to obtain low distortion, it is important that the selected transformer does not exhibit core saturation at full-scale. Excellent results are obtained with the Mini Circuits T1-6T or T1-1T. Proper termination of the input is important for input signal purity. A small capacitor across the inputs attenuates kickback-noise from the sample and hold. Series resistors as shown in Figure 6 may be advantageous to improve linearity. The VCM-node should be bypassed to ground as closed to the converter pin as possible using 100nF capacitors in parallel with a small one.

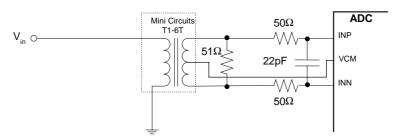


Figure 6. Example of AC coupled input using transformer configuration

If a DC-coupled single ended input is wanted, a solution based on operational amplifiers - as shown in Figure 7, is usually preferred. The AD826 is suggested for low distortion and video bandwidth. Lower cost operational amplifiers may be used if the demands are less strict. A good alternative for high performance applications is to use AD8138 single ended to differential amplifier.

nAD1070-18 10 Bit 70 MSPS Sampling ADC IP



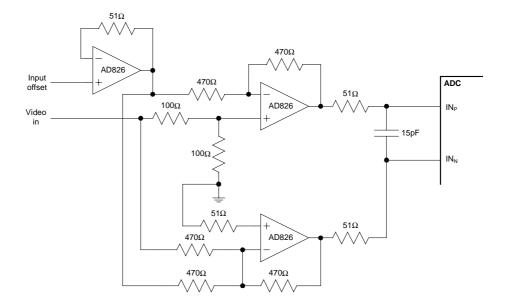


Figure 7. DC-coupled single ended to differential conversion (power supplies and bypassing not shown)

Clock

In order to preserve accuracy at high input frequency, it is important that the clock has low jitter and steep edges. Rise/fall times should be kept shorter than 2ns whenever possible. Overshoot should be avoided. Low jitter is especially important when converting high frequency input signals. Jitter causes the noise floor to rise proportionally to input signal frequency. Jitter may be caused by crosstalk on the PCB. It is therefore recommended that the clock trace on the PCB is made as short as possible.

Digital outputs

The digital output data appears in offset binary code at CMOS logic levels. Full-scale negative input results in output code 000...0. Full-scale positive input results in output code 111...1. Output data are available 6 clock cycles after the data are sampled. The analog input is sampled one aperture delay (t_{AP}) after the high to low clock transition. Output data should be sampled as shown in the timing diagram.

PCB layout and decoupling

A well designed PCB is necessary to get good spectral purity from any high performance ADC. A multilayer PCB with a solid ground plane is recommended for optimum performance. If the system has a split analog and digital ground plane, it is recommended that all ground pins on the ADC are connected to the analog ground plane. It is our experience that this gives the best performance. The power supply pins should be bypassed using 100nF surface mounted capacitors as close to the package pins as possible. Analog and digital supply pins should be separately filtered.

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Dynamic testing

Careful testing using high quality instrumentation is necessary to achieve accurate test results on high speed A/D-converters. It is important that the clock source and signal source has low jitter. A spectrally pure, low noise RF signal generator - such as the HP8662A or HP8644B is recommended for the test signal. Low pass filtering or band pass filtering of the input signal is usually necessary to obtain the required spectral purity (SFDR > 75dB). The clock signal can be obtained from either a crystal oscillator or a low-jitter pulse generator. Alternatively, a low-jitter RF-generator can be used as a clock source. At Nordic VLSI, the Marconi Instruments 2041A is used. The sinewave clock must then be applied to an ultra high-speed comparator (e.g. AD9696) and a TTL to CMOS level shifter (e.g. 74LV04) before application to the converter. The most consistent results are obtained if the clock signal is phase locked to the input signal. Phase locking allows testing without windowing of output data. A logic analyzer with deep memory - such as the HP16500-series, is recommended for test data acquisition.

Power Down Mode and Sleep Mode

The nAD1070-18 has both Power Down Mode and Sleep Mode. The Power Down Mode can be used when the ADC should be put to 'zero current consumption' state and when a somewhat longer startup time is allowed. The Sleep Mode can be used to put the ADC in an 'idle' state and when the application require a quick startup. The two different power consumption saving schemes can be activated through the PD, BIAS0 and BIAS1 pins/connections in the following manner:

Power Down Mode: PD=1, BIAS0=0, BIAS1=0 Sleep Mode: PD=0, BIAS0=0, BIAS1=0

The actual startup time from these modes are dependent on the external decopling configuration.

PRODUCT SPECIFICATION





DESIGN CENTER

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World Wide Web/Internet: Visit our site at http://www.nvlsi.no.

ORDERING INFORMATION

Type number	Description	Price
nAD1070-18-IC	nAD1070-18 sample in SSOP28 package	USD 50
	(limited availability)	
nAD1070-18-EVB	nAD1070-18 evaluation board including	USD 300
	characterisation report and user guide	

Table 5. Ordering information

Product Specification. Revision Date: August 31st, 2001

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